

MC74LCX244

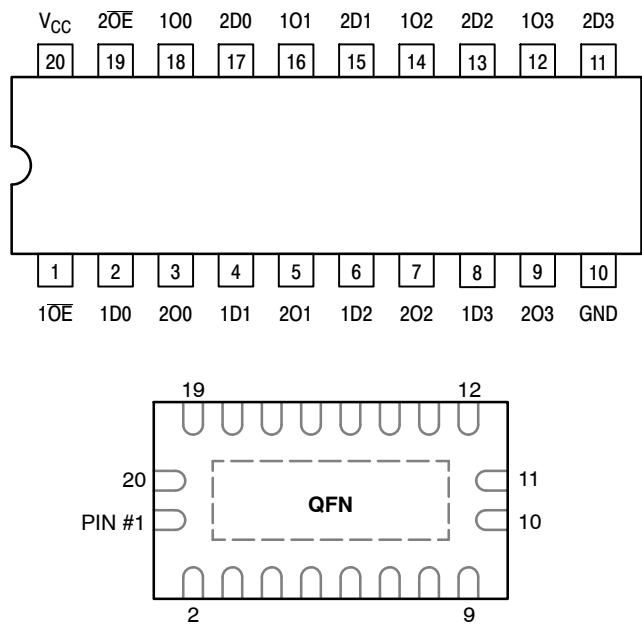


Figure 1. Pinouts: 20-Lead (Top View)

PIN NAMES

PINS	FUNCTION
nOE	Output Enable Inputs
1Dn, 2Dn	Data Inputs
1On, 2On	3-State Outputs

TRUTH TABLE

INPUTS		OUTPUTS
1OE 2OE	1Dn 2Dn	1On, 2On
L	L	L
L	H	H
H	X	Z

H = High Voltage Level
L = Low Voltage Level
Z = High Impedance State
X = High or Low Voltage Level and Transitions are Acceptable
For I_{CC} reasons, DO NOT FLOAT Inputs

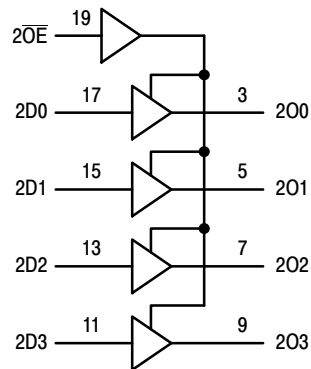
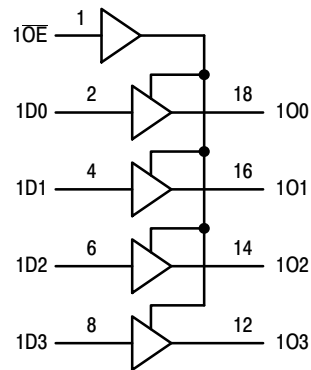


Figure 2. Logic Diagram

MC74LCX244

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V_{CC}	DC Supply Voltage	-0.5 to +7.0		V
V_I	DC Input Voltage	$-0.5 \leq V_I \leq +7.0$		V
V_O	DC Output Voltage	$-0.5 \leq V_O \leq +7.0$	Output in 3-State	V
		$-0.5 \leq V_O \leq V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I_{IK}	DC Input Diode Current	-50	$V_I < GND$	mA
I_{OK}	DC Output Diode Current	-50	$V_O < GND$	mA
		+50	$V_O > V_{CC}$	mA
I_O	DC Output Source/Sink Current	± 50		mA
I_{CC}	DC Supply Current Per Supply Pin	± 100		mA
I_{GND}	DC Ground Current Per Ground Pin	± 100		mA
T_{STG}	Storage Temperature Range	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit
V _{CC}	Supply Voltage Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
V _I	Input Voltage	0		5.5	V
V _O	Output Voltage (HIGH or LOW State) (3-State)	0 0		V _{CC} 5.5	V
I _{OH}	HIGH Level Output Current V _{CC} = 3.0 V – 3.6 V V _{CC} = 2.7 V – 3.0 V			–24 –12	mA
I _{OL}	LOW Level Output Current V _{CC} = 3.0 V – 3.6 V V _{CC} = 2.7 V – 3.0 V			24 12	mA
T _A	Operating Free–Air Temperature	–55		+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V _{IN} from 0.8 V to 2.0 V, V _{CC} = 3.0 V	0		10	ns/V

MC74LCX244

DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	T _A = -55°C to +125°C		Unit
			Min	Max	
V _{IH}	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V	1.7		V
		2.7 V ≤ V _{CC} ≤ 3.6 V	2.0		
V _{IL}	LOW Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	V
		2.7 V ≤ V _{CC} ≤ 3.6 V		0.8	
V _{OH}	HIGH Level Output Voltage	2.3 V ≤ V _{CC} ≤ 3.6 V; I _{OL} = 100 μA	V _{CC} - 0.2		V
		V _{CC} = 2.3 V; I _{OH} = -8 mA	1.8		
		V _{CC} = 2.7 V; I _{OH} = -12 mA	2.2		
		V _{CC} = 3.0 V; I _{OH} = -18 mA	2.4		
		V _{CC} = 3.0 V; I _{OH} = -24 mA	2.2		
V _{OL}	LOW Level Output Voltage	2.3 V ≤ V _{CC} ≤ 3.6 V; I _{OL} = 100 μA		0.2	V
		V _{CC} = 2.3 V; I _{OL} = 8 mA		0.6	
		V _{CC} = 2.7 V; I _{OL} = 12 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 16 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
I _I	Input Leakage Current	2.3 V ≤ V _{CC} ≤ 3.6 V; 0 V ≤ V _I ≤ 5.5 V		±5	μA
I _{OZ}	3-State Output Current	2.3 ≤ V _{CC} ≤ 3.6 V; 0 V ≤ V _O ≤ 5.5 V; V _I = V _{IH} or V _{IL}		±5	μA
I _{OFF}	Power-Off Leakage Current	V _{CC} = 0 V; V _I or V _O = 5.5 V		10	μA
I _{CC}	Quiescent Supply Current	2.3 ≤ V _{CC} ≤ 3.6 V; V _I = GND or V _{CC}		10	μA
		2.3 ≤ V _{CC} ≤ 3.6 V; 3.6 ≤ V _I or V _O ≤ 5.5 V		±10	
ΔI _{CC}	Increase in I _{CC} per Input	2.3 ≤ V _{CC} ≤ 3.6 V; V _{IH} = V _{CC} - 0.6 V		500	μA

2. These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS (t_R = t_F = 2.5 ns; R_L = 500 Ω)

Symbol	Parameter	Waveform	Limits						Unit
			T _A = -55°C to +125°C						
			V _{CC} = 3.0 V to 3.6 V		V _{CC} = 2.7 V		V _{CC} = 2.5 V ±0.2		
			C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
			Min	Max	Min	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation Delay Input to Output	1	1.5	6.5	1.5	7.5	1.5	7.8	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	2	1.5	8.0	1.5	9.0	1.5	10	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	1.5	7.0	1.5	8.0	1.5	8.4	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 3)			1.0					ns

3. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSSL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

MC74LCX244

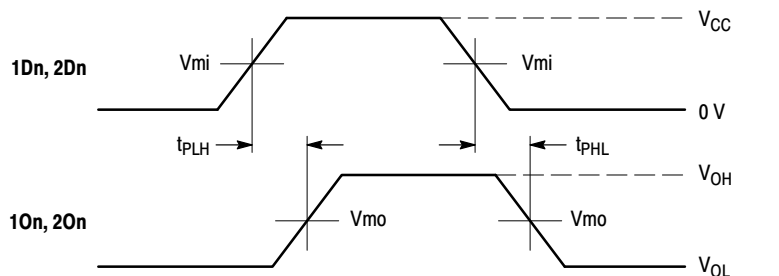
DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = +25^\circ\text{C}$			Unit
			Min	Typ	Max	
V_{OLP}	Dynamic LOW Peak Voltage (Note 4)	$V_{CC} = 3.3\text{ V}, C_L = 50\text{ pF}, V_{IH} = 3.3\text{ V}, V_{IL} = 0\text{ V}$ $V_{CC} = 2.5\text{ V}, C_L = 30\text{ pF}, V_{IH} = 2.5\text{ V}, V_{IL} = 0\text{ V}$		0.8 0.6		V
V_{OLV}	Dynamic LOW Valley Voltage (Note 4)	$V_{CC} = 3.3\text{ V}, C_L = 50\text{ pF}, V_{IH} = 3.3\text{ V}, V_{IL} = 0\text{ V}$ $V_{CC} = 2.5\text{ V}, C_L = 30\text{ pF}, V_{IH} = 2.5\text{ V}, V_{IL} = 0\text{ V}$		-0.8 -0.6		V

4. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

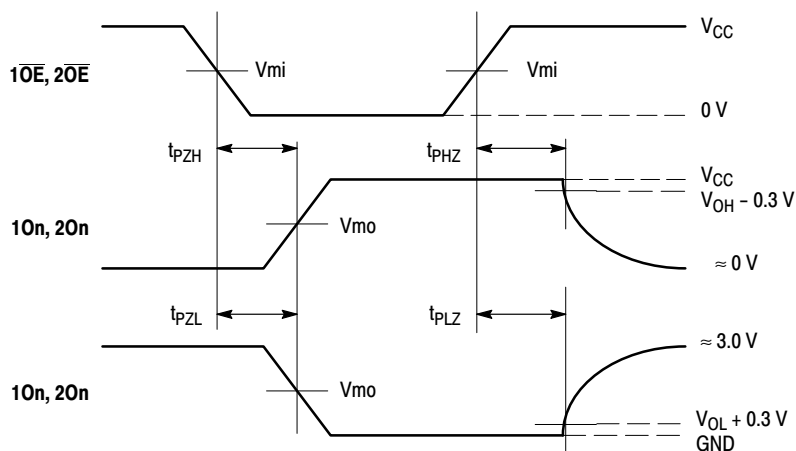
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C_{IN}	Input Capacitance	$V_{CC} = 3.3\text{ V}, V_I = 0\text{ V or } V_{CC}$	7	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.3\text{ V}, V_I = 0\text{ V or } V_{CC}$	8	pF
C_{PD}	Power Dissipation Capacitance	10 MHz, $V_{CC} = 3.3\text{ V}, V_I = 0\text{ V or } V_{CC}$	25	pF



WAVEFORM 1 - PROPAGATION DELAYS

$t_R = t_F = 2.5\text{ ns}$, 10% to 90%; $f = 1\text{ MHz}$; $t_W = 500\text{ ns}$



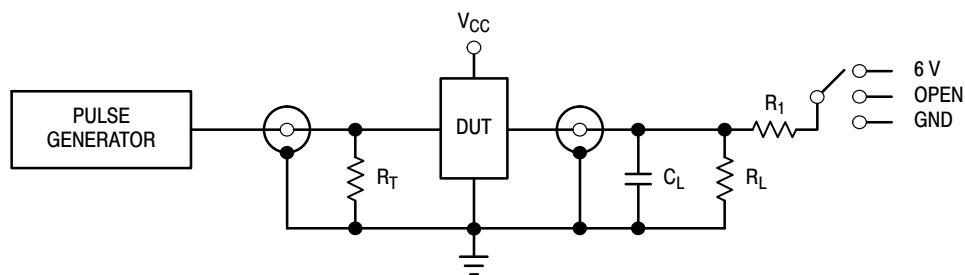
WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

$t_R = t_F = 2.5\text{ ns}$, 10% to 90%; $f = 1\text{ MHz}$; $t_W = 500\text{ ns}$

Figure 3. AC Waveforms

Symbol	V_{CC}		
	$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$2.5\text{ V} \pm 0.2\text{ V}$
V_{mi}	1.5 V	1.5 V	$V_{CC}/2$
V_{mo}	1.5 V	1.5 V	$V_{CC}/2$
V_{HZ}	$V_{OL} + 0.3\text{ V}$	$V_{OL} + 0.3\text{ V}$	$V_{OL} + 0.15\text{ V}$
V_{LZ}	$V_{OH} - 0.3\text{ V}$	$V_{OH} - 0.3\text{ V}$	$V_{OH} - 0.15\text{ V}$

MC74LCX244



TEST	SWITCH
t_{PLH} , t_{PHL}	Open
t_{PZL} , t_{PLZ}	6 V at $V_{CC} = 3.3 \pm 0.3$ V 6 V at $V_{CC} = 2.5 \pm 0.2$ V
Open Collector/Drain t_{PLH} and t_{PHL}	6 V
t_{PZH} , t_{PHZ}	GND

$C_L = 50$ pF at $V_{CC} = 3.3 \pm 0.3$ V or equivalent (includes jig and probe capacitance)
 $C_L = 30$ pF at $V_{CC} = 2.5 \pm 0.2$ V or equivalent (includes jig and probe capacitance)
 $R_L = R_1 = 500 \Omega$ or equivalent
 $R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 4. Test Circuit

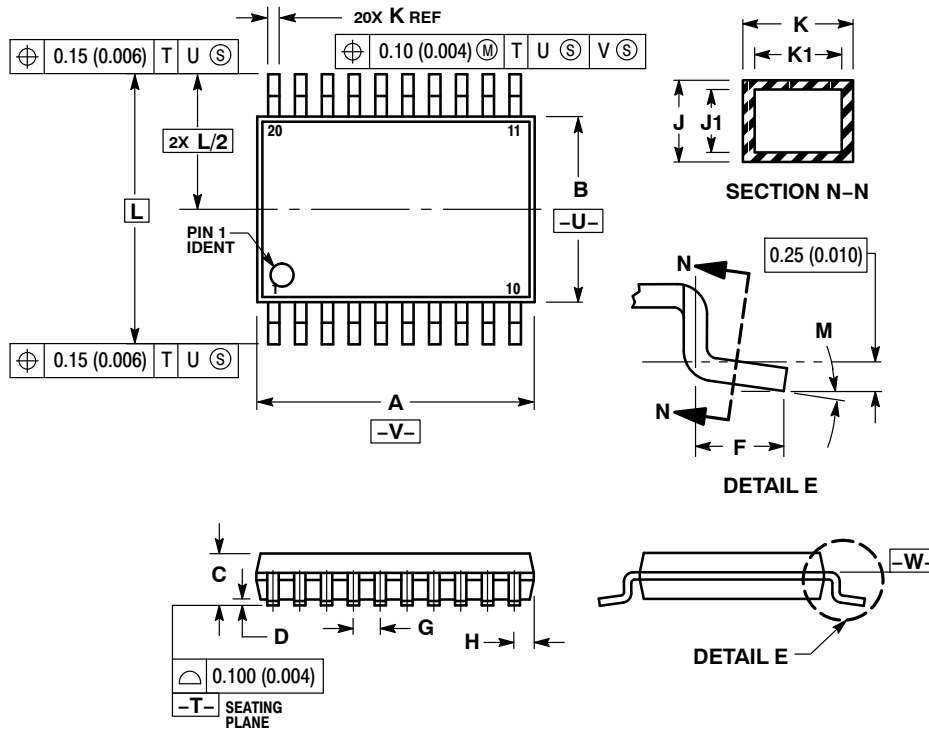
ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX244DW	SOIC-20	38 Units / Rail
MC74LCX244DWG	SOIC-20 (Pb-Free)	
MC74LCX244DWR2	SOIC-20	1000 / Tape & Reel
MC74LCX244DWR2G	SOIC-20 (Pb-Free)	
MC74LCX244DT	TSSOP-20*	75 Units / Rail
MC74LCX244DTG	TSSOP-20*	
MC74LCX244DTR2	TSSOP-20*	2500 / Tape & Reel
MC74LCX244DTR2G	TSSOP-20*	
MC74LCX244MELG	SOEIAJ-20 (Pb-Free)	2000 / Tape & Reel
MC74LCX244MNTWG	QFN20 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb-Free.

MC74LCX244

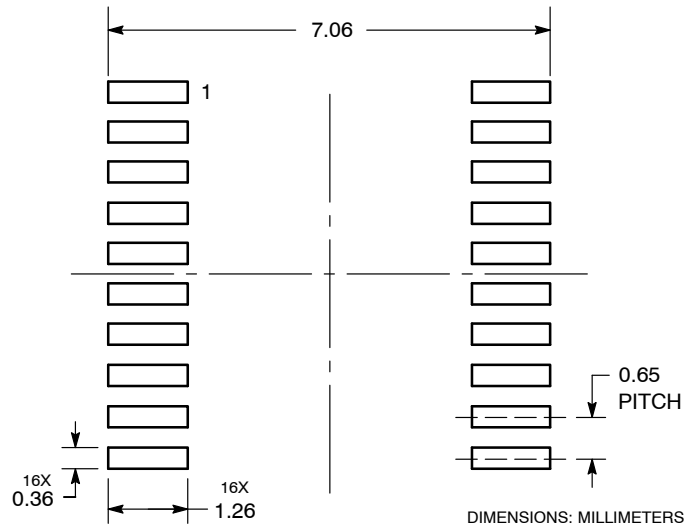
TSSOP-20
CASE 948E-02
ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*

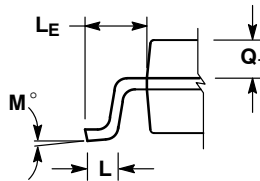
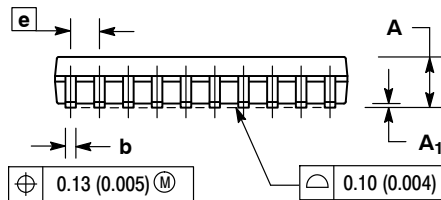
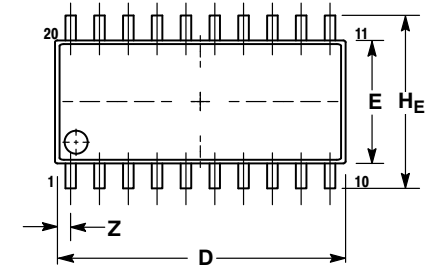


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

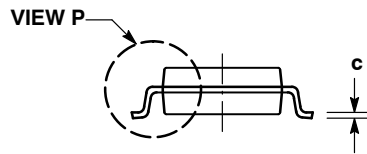
MC74LCX244

PACKAGE DIMENSIONS

SOEIAJ-20
CASE 967-01
ISSUE A



DETAIL P



NOTES:

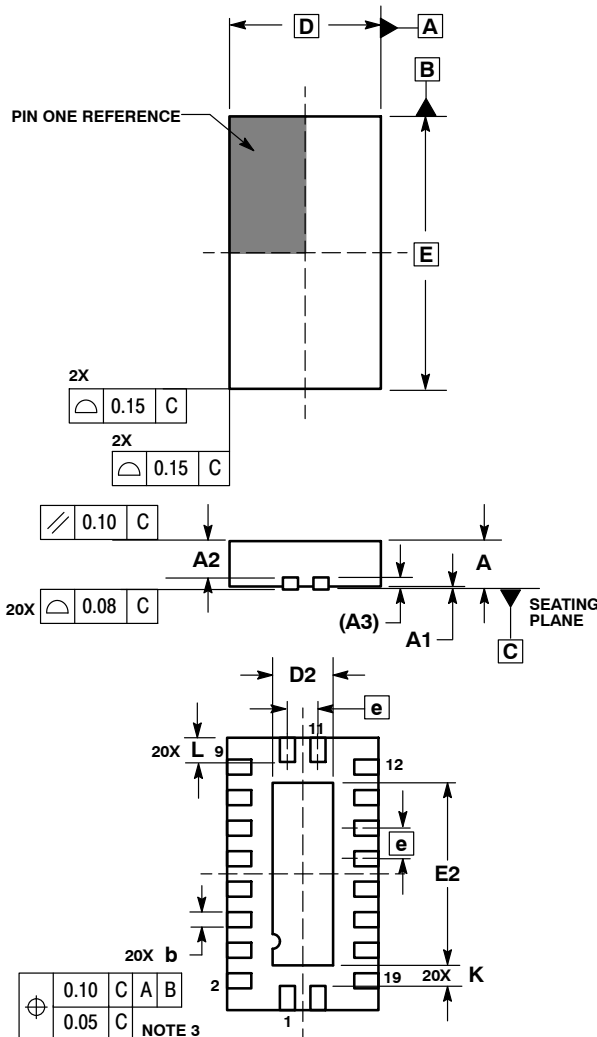
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.15	0.25	0.006	0.010
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

MC74LCX244

PACKAGE DIMENSIONS

QFN20
CASE 485AA-01
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A2	0.65	0.75
A3	0.20	REF
b	0.20	0.30
D	2.50	BSC
D2	0.85	1.15
E	4.50	BSC
E2	2.85	3.15
e	0.50	BSC
K	0.20	---
L	0.35	0.45

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